Very Low Forward Voltage Trench-based Schottky Rectifier

Exceptionally Low $V_F = 0.50 \text{ V}$ at $I_F = 5 \text{ A}$

Features

- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- These are Pb-Free Devices

Typical Applications

- Switching Power Supplies including Notebook / Netbook Adapters, ATX and Flat Panel Display
- High Frequency and DC-DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Maximum for 10 sec

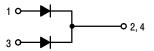


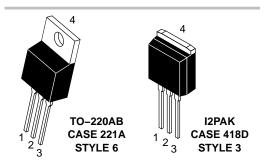
ON Semiconductor®

www.onsemi.com

VERY LOW FORWARD VOLT-AGE, LOW LEAKAGE SCHOT-TKY BARRIER RECTIFIERS 30 AMPERES, 120 VOLTS

PIN CONNECTIONS









ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	120	V
Average Rectified Forward Current (Rated V _R , T _C = 125°C)	Per device Per diode	I _{F(AV)}	30 15	A
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 130°C)	Per device Per diode	I _{FRM}	60 30	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)		I _{FSM}	150	А
Operating Junction Temperature		TJ	-40 to +150	°C
Storage Temperature		T _{stg}	-40 to +150	°C
Voltage Rate of Change (Rated V _R)		dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Rating	Symbol	NTST30120CTG NTSB30120CT-1G	NTSB30120CTG	NTSJ30120CTG	Unit
Maximum Thermal Resistance per Diode Junction-to-Case Junction-to-Ambient	$R_{ heta JC} \ R_{ heta JA}$	2.5 70	1.14 46.6	4.05 105	°C/W

ELECTRICAL CHARACTERISTICS (Per Leg unless otherwise noted)

Rating	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 1)	٧ _F			V
$(I_F = 5 \text{ A}, T_J = 25^{\circ}\text{C})$		0.56	_	
$(I_F = 7.5 \text{ A}, T_J = 25^{\circ}\text{C})$		0.71	_	
$(I_F = 15 \text{ A}, T_J = 25^{\circ}\text{C})$		0.90	1.08	
$(I_F = 5 \text{ A}, T_J = 125^{\circ}\text{C})$		0.50	_	
$(I_F = 7.5 \text{ A}, T_J = 125^{\circ}\text{C})$		0.60	_	
$(I_F = 15 \text{ A}, T_J = 125^{\circ}\text{C})$		0.68	0.76	
Maximum Instantaneous Reverse Current (Note 1)	I _R			
$(V_R = 90 \text{ V}, T_J = 25^{\circ}\text{C})$		16	_	μΑ
$(V_R = 90 \text{ V}, T_J = 125^{\circ}\text{C})$		11	_	mA
(Rated dc Voltage, T _{.I} = 25°C)		_	800	μΑ
(Rated dc Voltage, T _J = 125°C)		25	100	mΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width = $300 \,\mu s$, Duty Cycle $\leq 2.0\%$

TYPICAL CHARACTERISITICS

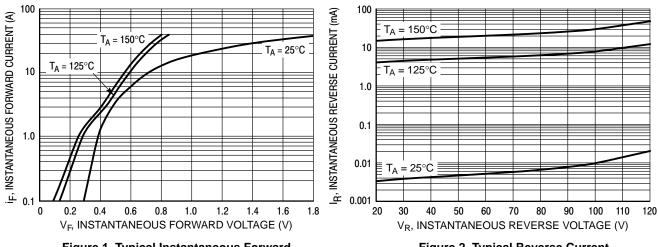


Figure 1. Typical Instantaneous Forward Characteristics

Figure 2. Typical Reverse Current Characteristics

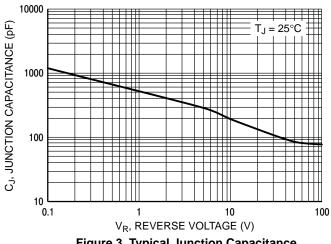


Figure 3. Typical Junction Capacitance

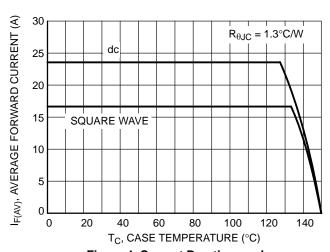
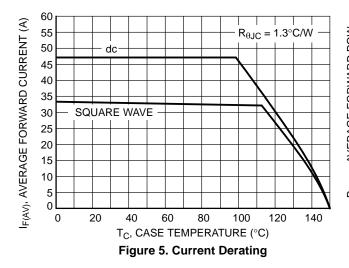


Figure 4. Current Derating per Leg



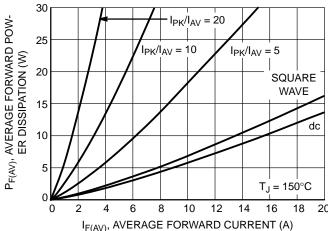


Figure 6. Forward Power Dissipation

TYPICAL CHARACTERISITICS

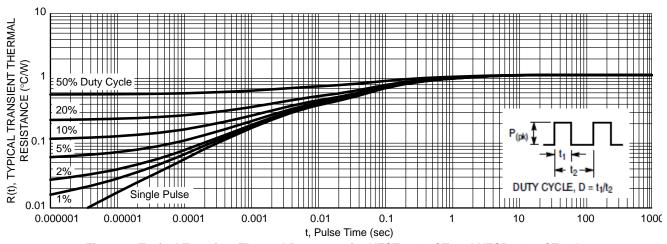


Figure 7. Typical Transient Thermal Response for NTST30120CT and NTSB30120CT-1G

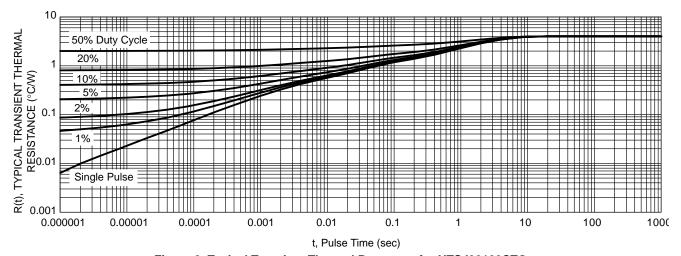


Figure 8. Typical Transient Thermal Response for NTSJ30120CTG

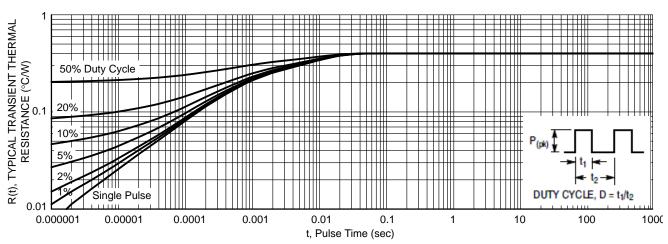


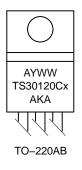
Figure 9. Typical Transient Thermal Response for NTSB30120CTG

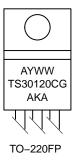
ORDERING INFORMATION

Device	Package	Shipping [†]
NTST30120CTG	TO-220AB (Pb-Free)	50 Units / Rail
NTSJ30120CTG	TO-220FP (Halide-Free)	50 Units / Rail
NTSB30120CT-1G	I ² PAK (Pb-Free)	50 Units / Rail
NTSB30120CTG	D ² PAK (Pb-Free)	50 Units / Rail
NTSB30120CTT4G	D ² PAK (Pb-Free)	800 / Tape & Reel

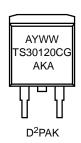
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MARKING DIAGRAMS









A = Assembly Location

Y = Year

WW = Work Week
AKA = Polarity Designator

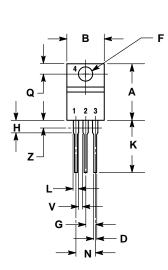
x = G or H

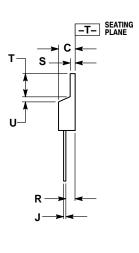
G = Pb-Free Package

H = Halide-Free Package

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH**





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

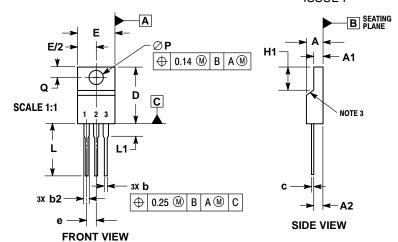
	INCHES		MILLIN	IETERS
DIM	MIN MAX		MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
C	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 6:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

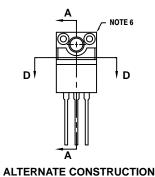
PACKAGE DIMENSIONS

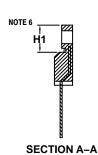
TO-220 FULLPACK, 3-LEAD

CASE 221AH ISSUE F









- DIMENSIONING AND TOLERANCING PER ASME

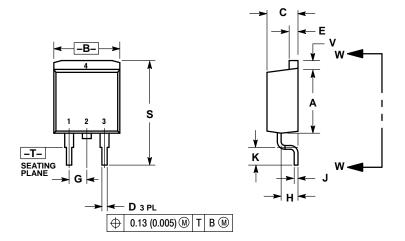
- DIMENSIONING AND TOLERANCING PER ASME
 Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 CONTOUR UNCONTROLLED IN THIS AREA.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE
 PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO
 EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE
 MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY.
 DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION.
 LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.
 CONTOURS AND FEATURES OF THE MOLDED PACKAGE BODY
 MAY VARY WITHIN THE ENVELOP DEFINED BY DIMENSIONS A1
 AND H1 FOR MANUFACTURING PURPOSES.

 MILLIMETERS

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.30	4.70	
A1	2.50	2.90	
A2	2.50	2.90	
b	0.54	0.84	
b2	1.10	1.40	
C	0.49	0.79	
D	14.70	15.30	
Е	9.70	10.30	
е	2.54	BSC	
H1	6.60	7.10	
L	12.50	14.73	
L1		2.80	
Р	3.00	3.40	
O	2 80	3 20	

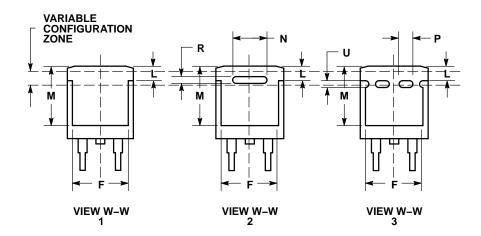
PACKAGE DIMENSIONS

D²PAK 3 CASE 418B-04 ISSUE K



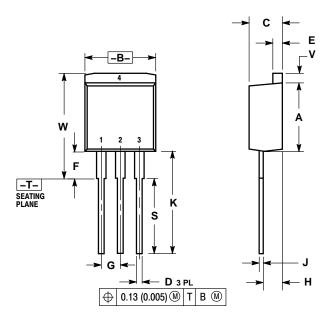
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETER		
DIM	MIN	MAX	MIN	MAX	
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
Е	0.045	0.055	1.14	1.40	
F	0.310	0.350	7.87	8.89	
G	0.100	0.100 BSC		BSC	
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
K	0.090	0.110	2.29	2.79	
L	0.052	0.072	1.32	1.83	
M	0.280	0.320	7.11	8.13	
N	0.197 REF		5.00 REF		
Р	0.079 REF		2.00 REF		
R	0.039	REF	0.99	REF	
S	0.575	0.625	14.60	15.88	
٧	0.045	0.055	1.14	1.40	



PACKAGE DIMENSIONS

I²PAK (TO-262) CASE 418D ISSUE D



- 1. DIMENSIONING AND TOLERANCING PER ANSI
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.335	0.380	8.51	9.65
В	0.380	0.406	9.65	10.31
C	0.160	0.185	4.06	4.70
D	0.026	0.035	0.66	0.89
E	0.045	0.055	1.14	1.40
F	0.122 REF		3.10 REF	
G	0.100	BSC	2.54	BSC
Н	0.094	0.110	2.39	2.79
J	0.013	0.025	0.33	0.64
K	0.500	0.562	12.70	14.27
S	0.390 REF		9.90	REF
٧	0.045	0.070	1.14	1.78
W	0.522	0.551	13.25	14.00

STYLE 3:

- PIN 1. ANODE 2. CATHODE
 - ANODE
 - 4. CATHODE

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

N. American Technical Support: 800-282-9855 Toll Free

Europe, Middle East and Africa Technical Support:

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative